

Data Sheet

Rev. 2.8 / May 2011

ZSC31010

RBic_{Lite}[™] Low-Cost Sensor Signal Conditioner







Brief Description

The RBic_{Lite}[™] ZSC31010 is a sensor signal conditioner integrated circuit, which enables easy and precise calibration of resistive bridge sensors via EEPROM. When mated to a resistive bridge sensor, it will digitally correct offset and gain with the option to correct offset and gain coefficients and linearity over temperature. A second-order compensation can be enabled for temperature coefficients of gain or offset or bridge linearity. The RBic_{Lite}[™] communicates via ZMDI's ZACwire[™] serial interface to the host computer and is easily mass calibrated in a Windows® environment. Once calibrated, the output pin Sig[™] can provide selectable 0 to 1 V, rail-to-rail ratiometric analog output, or digital serial output of bridge data with optional temperature data.

Features

- Digital compensation of sensor offset, sensitivity, temperature drift, and non-linearity
- Accommodates differential sensor signal spans, from 1.2 mV/V to 60 mV/V
- ZACwire[™] One-Wire Interface (OWI)
- Internal temperature compensation and detection via bandgap PTAT (proportional to absolute temperature)
- Output options: rail-to-rail analog output voltage, absolute analog voltage, digital ZACwire[™] One-Wire Interface (OWI)
- Optional sequential output of both temperature and bridge readings on ZACwire™ digital output
- Fast response time, 1 ms (typical)
- High voltage protection up to 30 V with external JFET
- Chopper-stabilized true differential ADC
- Buffered and chopper-stabilized output DAC

Benefits

- No external trimming components required
- PC-controlled configuration and calibration via ZACwire[™] One-Wire Interface – simple, low cost
- High accuracy (±0.1% FSO @ -25 to 85°C; ±0.25% FSO @ -50 to 150°C)
- Single pass calibration quick and precise
- Suitable for battery-powered applications
- Small SOP8 package

Available Support

- Development Kit available
- Multi-Unit Calibrator Kit available
- Support for industrial mass calibration available
- Quick circuit customization possible for large production volumes

Physical Characteristics

- Supply voltage 2.7 to 5.5 V, with external JFET 5.5V to 30 V
- Current consumption depending on adjusted sample rate: 0.25 mA to 1 mA
- Wide operational temperature: -50 to +150°C

ZSC31010 Application Circuit – Digital Output



© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8

All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.

RBic_{Lite}™ Low-Cost Sensor Signal Conditioner





ZSC31010 Block Diagram

Highly Versatile Applications in Many Markets Including

- Industrial
- Building Automation
- Office Automation
- White Goods
- Automotive
- Portable Devices
- Your Innovative Designs



Rail-to-Rail Ratiometric Voltage Output Applications



Absolute Analog Voltage Output Applications



Ordering Examples (Please contact ZMDI Sales for additional options.)

Sales Code	Description	Package
ZSC31010CEB	ZSC31010 RBic _{Lite} ™ Die — Temperature range: -50°C to +150°C	Unsawn on Wafer
ZSC31010CEC	ZSC31010 RBic _{Lite} ™ Die — Temperature range: -50°C to +150°C	Sawn on Wafer Frame
ZSC31010CED	ZSC31010 RBic _{Lite} ™ Die — Temperature range: -50°C to +150°C	Waffle Pack
ZSC31010CEG1	ZSC31010 RBic _{Lite} ™ SOP8 (150 mil) — Temperature range: -50°C to +150°C	Tube: add "-T" to sales code Reel: add "-R"
ZSC31010KIT	ZSC31010 SSC Evaluation Kit: Communication Board, SSC Board, Sensor Replacement Board, Evaluation Software, USB Cable, 5 IC Samples	Kit

Sales and Further Info	rmation	www.zmdi.com	SSC@zmdi.com
Zentrum Mikroelektronik Dresden AG Grenzstrasse 28 01109 Dresden Germany	ZMD America, Inc. 8413 Excelsior Drive Suite 200 Madison, WI 53717 USA	Zentrum Mikroelektronik Dresden AG, Japan Office 2nd Floor, Shinbashi Tokyu Bldg. 4-21-3, Shinbashi, Minato-ku Tokyo, 105-0004 Japan	ZMD FAR EAST, Ltd. 3F, No. 51, Sec. 2, Keelung Road 11052 Taipei Taiwan
Phone +49 (0)351.8822.7.772 Fax +49 (0)351.8822.8.7772	Phone +1 (608) 829-1987 Fax +1 (631) 549-2882	Phone +81.3.6895.7410 Fax +81.3.6895.7301	Phone +886 2 2377 8189 Fax +886 2 2377 8199

DISCLAIMER: This information applies to a product under development. Its characteristics and specifications are subject to change without notice. Zentrum Mikroelektronik Dresden AG (ZMD AG) assumes no obligation regarding future manufacture unless otherwise agreed to in writing. The information furnished hereby is believed to be true and accurate. However, under no circumstances shall ZMD AG be liable to any customer, licensee, or any other third party for any special, indirect, incidental, or consequential damages of any kind or nature whatsoever arising out of or in any way related to the furnishing, performance, or use of this technical data. ZMD AG hereby expressly disclaims any liability of ZMD AG to any customer, licensee or any other third party hereby waives any liability of ZMD AG normation with or arising out of the furnishing, performance or use of this technical data, whether based on contract, warranty, tort (including negligence), strict liability, or otherwise.

© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8

All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner.

Contents

1	Elect	rical Characteristics	8
	1.1. A	bsolute Maximum Ratings	8
	1.2. R	ecommended Operating Conditions	8
	1.3. E	lectrical Parameters	9
	1.3.1	Supply / Regulation Characteristics	9
	1.3.2	Analog Front-End (AFE) Characteristics	9
	1.3.3	EEPROM Parameters	9
	1.3.4	A/D Converter Characteristics	10
	1.3.5	Analog Output (DAC and Buffer) Characteristics	10
	1.3.6	ZACwire™ Serial Interface	10
	1.3.7	System Response Characteristics	11
	1.4. A	nalog Inputs versus Output Resolution	11
2	Circu	it Description	14
	2.1. S	ignal Flow and Block Diagram	14
	2.2. A	nalog Front End	15
	2.2.1	Bandgap/PTAT and PTAT Amplifier	15
	2.2.2	Bridge Supply	15
	2.2.3	PREAMP Block	15
	2.2.4	Analog-to-Digital Converter (ADC)	15
	2.3. D	igital Signal Processor	16
	2.3.1	EEPROM	17
	2.3.2	One-Wire Interface - ZACwire™	17
	2.4. C	utput Stage	18
	2.4.1	Digital to Analog Converter (Output DAC)	18
	2.4.2	Output Buffer	18
	2.4.3	Voltage Reference Block	18
	2.5. C	lock Generator / Power-On Reset (CLKPOR)	19
	2.5.1	Trimming the Oscillator	20
3	Func	tional Description	21
-	3.1. C	eneral Working Mode	21
	-		





RBic_{Lite}™ Low-Cost Sensor Signal Conditioner

RBic_{Lite}™ Low-Cost Sensor Signal Conditioner





3.2. ZACwire [™] Communication Interface	.22
3.2.1. Properties and Parameters	.22
3.2.2. Bit Encoding	.22
3.2.3. Write Operation from Master to RBic _{Lite} ™	.23
3.2.4. RBIC _{Lite} ™ Read Operations	.23
3.2.5. High Level Protocol	.26
3.3. Command/Data Bytes Encoding	.27
3.4. Calibration Sequence	.28
3.5. EEPROM Bits	.30
3.6. Calibration Math	.32
3.6.1. Correction Coefficients	.32
3.6.2. Interpretation of Binary Numbers for Correction Coefficients	.33
3.7. Reading EEPROM Contents	.37
Application Circuit Examples	.38
I.1. Three-Wire Rail-to-Rail Ratiometric Output	.38
I.2. Absolute Analog Voltage Output	.39
I.3. Three-Wire Ratiometric Output with Over-Voltage Protection	.40
I.4. Digital Output	.41
I.5. Output Short Protection	.41
Default EEPROM Settings	.42
Pin Configuration and Package	.43
ESD/Latch-Up-Protection	.44
Test	.44
Quality and Reliability	.44
Customization	.44
Ordering Examples	.44
Related Documents	.45
Definitions of Acronyms	.45
Document Revision History	.46
	 3.2. ZACwire [™] Communication Interface





List of Figures

Figure 2.1	RBic _{Lite} ™ ZSC31010 Block Diagram	14
Figure 2.2	DAC Output Timing for Highest Update Rate	18
Figure 3.1	General Working Mode	21
Figure 3.2	Manchester Duty Cycle	22
Figure 3.3	19-Bit Write Frame	23
Figure 3.4	Read Acknowledge	23
Figure 3.5	Digital Output (NOM) Bridge Readings	24
Figure 3.6	Digital Output (NOM) Bridge Readings with Temperature	24
Figure 3.7	Read EEPROM Contents	25
Figure 3.8	Transmission of a Number of Data Packets	25
Figure 3.9	ZACwire [™] Output Timing for Lower Update Rates	26
Figure 4.1	Rail-to-Rail Ratiometric Voltage Output	38
Figure 4.2	Absolute Analog Voltage Output	39
Figure 4.3	Ratiometric Output, Temperature Compensation via Internal Diode	40
Figure 6.1	RBic _{Lite} ™ Pin-Out Diagram	43

List of Tables

Table 1.1	Absolute Maximum Ratings	8
Table 1.2	Recommended Operating Conditions	8
Table 1.3	Supply / Regulation Characteristics	9
Table 1.4	Parameters for Analog Front-End (AFE)	9
Table 1.5	EEPROM Parameters	9
Table 1.6	Parameters for A/D Converter	10
Table 1.7	Parameters for Analog Output (DAC and Buffer)	10
Table 1.8	Parameters for ZACwire™ Serial Interface	10
Table 1.9	Parameters for System Response	11
Table 1.10	ADC Resolution Characteristics for an Analog Gain of 6	11
Table 1.11	ADC Resolution Characteristics for an Analog Gain of 12	12
Table 1.12	ADC Resolution Characteristics for an Analog Gain of 24	12
Table 1.13	ADC Resolution Characteristics for an Analog Gain of 48	13
Table 2.1	Order of Trim Codes	19
Table 2.2	Oscillator Trimming	20
Table 3.1	Pin Configuration and Latch-Up Conditions	22
Table 3.2	Total Transmission Time for Different Update Rate Settings and Output Configuration	25
Table 3.3	Special Measurement versus Update Rate	26
Table 3.4	Command/Data Bytes Encoding	27
Table 3.5	Programming Details for Command 30 _H	27
Table 3.6	ZSC31010 EEPROM Bits	

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	6 of 46
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	0 01 40





Correction Coefficients	
Gain_B[13:0] Weightings	
Offset_B Weightings	
Gain_T Weightings	
Offset_T Weightings	35
EEPROM Read Order	
Resistor Values for Short Protection	41
Factory Settings for the ZSC31010 EEPROM	42
Storage and Soldering Conditions for the SOP-8 Package	43
RBic _{Lite} ™ Pin Configuration	43
	Correction Coefficients Gain_B[13:0] Weightings Offset_B Weightings Gain_T Weightings Offset_T Weightings EEPROM Read Order Resistor Values for Short Protection Factory Settings for the ZSC31010 EEPROM Storage and Soldering Conditions for the SOP-8 Package RBicLite [™] Pin Configuration

© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.

RBic_{Lite}™ Low-Cost Sensor Signal Conditioner





1 Electrical Characteristics

1.1. Absolute Maximum Ratings

Table 1.1 Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit	Conditions
V _{DD}	Analog Supply Voltage	-0.3	6.0	V	
V _{INA}	Voltages at Analog I/O – In Pin	-0.3	VDD+0.3	V	
V _{OUTA}	Voltages at Analog I/O – Out Pin	-0.3	VDD+0.3	V	
T _{STG}	Storage Temperature Range	-50	150	°C	
T _{STG <10h}	Storage Temperature Range	-50	170	°C	For periods < 10 hours

Note: Also see Table 6.1 regarding soldering temperature and storage conditions for the SOP-8 package.

1.2. Recommended Operating Conditions

Table 1.2 Recommended Operating Conditions

Symbol	Parameter	Min	Тур	Max	Unit	Conditions
V _{DD}	Analog Supply Voltage to Ground	2.7	5.0	5.5	V	
V _{SUPP}	Analog Supply Voltage (with external JFET Regulator)	5.5	7	30	V	
V _{CM}	Common Mode Voltage	1		V _{DDA} - 1.3	V	
Т _{АМВ}	Ambient Temperature Range	-50		150	°C	
C _{VDD}	External Capacitance between V_{DD} and Ground	100	220	470	nF	
R _{L,OUT}	Output Load Resistance to V_{SS} or V_{DD} $^{3)}$	2.5	10		kΩ	
C _{L,OUT}	Output Load Capacitance 4)		10	15	nF	
R _{BR}	Bridge Resistance 5)	0.2		100	kΩ	
tPON	Power ON Rise Time			100	ms	

¹⁾ Note that the maximum calibration temperature is 85°C.

²⁾ If buying die, designers should use caution not to exceed maximum junction temperature by proper package selection.

³⁾ When using the output for digital calibration, no pull down resistor is allowed.

⁴⁾ Using the output for digital calibration, $C_{L,OUT}$ is limited by the maximum rise time $T_{ZAC,rise}$.

⁵⁾ Note: Minimum bridge resistance is only a factor if using the Bsink feature. The nominal R_{DS}(ON) of the Bsink transistor is 10 Ω when operating at V_{DD} = 5 V, and 15 Ω when operating at V_{DD} = 3.0 V. This does give rise to a ratiometricity inaccuracy that becomes greater with low bridge resistances.

Data Sheet May 25, 2011





1.3. Electrical Parameters

1.3.1. Supply / Regulation Characteristics

Table 1.3 Supply / Regulation Characteristics

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Supply Voltage	V _{DD}	2.7	5.0	5.5	V	
Supply Current (varies with	I _{DD}		0.25		m۸	At minimum update rate
update rate and output mode)			1.0	1.2	ША	At maximum update rate
Temperature Coefficient –	TC _{REG}			35	nnm/k	Tem10°C to 120°C
Regulator (worst case) *				100	ppm/K	Temp. < -10°C and > 120°C
Power Supply Rejection Ratio *	PSRR	60			dB	DC < 100 Hz (JFET regulation loop using mmbf4392 and 0.1 μ F decoupling cap)
		45			dB	AC < 100 kHz (JFET regulation loop using mmbf4392 and 0.1 μ F decoupling cap)
Power-On Reset Level	POR	1.4		2.6	V	

1.3.2. Analog Front-End (AFE) Characteristics

Table 1.4 Parameters for Analog Front-End (AFE)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Leakage Current Pin VBP,VBN	I _{IN_LEAK}			±10	nA	

1.3.3. EEPROM Parameters

Table 1.5EEPROM Parameters

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Number Write Cycles	N _{WRI_EEP}	At 150°C At 85°C			100 100k	Cycles
Data Retention	t _{WRI_EEP}	At 100°C			10	Years

^{*} No verification in mass production; parameter is guaranteed by design and/or quality observation.





1.3.4. A/D Converter Characteristics

Table 1.6 Parameters for A/D Converter

Parameter	Symbol	Min	Тур	Max	Unit	Conditions		
ADC Resolution	r _{ADC}		14		Bit			
Integral Nonlinearity (INL) ¹⁾	INLADC	-4		+4	LSB			
Differential Nonlinearity (DNL) *	DNL _{ADC}	-1		+1	LSB			
Response Time T _{RES,ADC} 1 ms Varies with update rate. V given at fastest rate.						Varies with update rate. Value given at fastest rate.		
¹⁾ Note: This is ± 4 LSBs to the 14-bit A-to-D conversion. This implies absolute accuracy to 12 bits on the A-to-D result. Non-linearity is typically better at temperatures less than 125°C.								

1.3.5. Analog Output (DAC and Buffer) Characteristics

Table 1.7 Parameters for Analog Output (DAC and Buffer)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Max. Output Current	I _{OUT}	2.2			mA	Max. current maintaining accuracy
Resolution	r _{out}			11	Bit	Referenced to V _{DD}
Absolute Error	E _{ABS}	-10		+10	mV	DAC input to output
Differential Nonlinearity [†]	DNL	-0.9		+1.5	LSB _{11Bit}	No missing codes
Upper Output Voltage Limit	V _{OUT}	95%			V _{DD}	R _L = 2.5 kΩ
Lower Output Voltage Limit	V _{OUT}			16.5	mV	

1.3.6. ZACwire[™] Serial Interface

Table 1.8 Parameters for ZACwire[™] Serial Interface

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
ZACwire [™] Line Resistance [*]	R _{ZAC,line}			3.9	kΩ	The rise time must be $T_{ZAC,rise}$ =
ZACwire [™] Load Capacitance [*]	$C_{ZAC,load}$	0	1	15	nF	$2 * R_{ZAC,line} * C_{ZACload} \le 5\mu s$. If using a pull-up resistor instead of a line resistor, it must meet this specification.
ZACwire [™] Rise Time [*]	T _{ZAC,rise}			5	μs	
Voltage Level Low *	V _{ZAC,low}		0	0.2	V_{DD}	
Voltage Level High [*]	V _{ZAC,low}	0.8	1		V_{DD}	

[†] No verification in mass production; parameter is guaranteed by design and/or quality observation.





1.3.7. System Response Characteristics

Table 1.9	Parameters	for Sy	ystem	Response
-----------	------------	--------	-------	----------

Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
Start-Up-Time	t _{STA}			10	ms	Power-up to output	
Response Time	t _{RESP}		1	2	ms	Update_rate = 1 kHz (1 ms)	
Sampling Rate	f₅		1000		Hz	Update_rate = 1 kHz (1 ms)	
Overall Linearity Error	E _{LIND}		0.025	0.04	%	Bridge input to output – Digital	
Overall Linearity Error	Elina		0.1	0.2	%	Bridge input to output – Analog	
Overall Ratiometricity Error	RE _{out}			0.035	%	±10%VDD, Not using Bsink feature	
Overall Accuracy – Digital	ACoutD			±0.1%	0/ ESO	-25°C to 85°C	
(only IC, without sensor bridge)				±0.25%	%F3U	-50°C to 150°C	
	ACoutA			±0.25%		-25°C to 85°C	
Overall Accuracy – Analog (only IC, without sensor bridge) ^{1) 2)}				±0.35%	%FSO	-40°C to 125°C	
(only 10, without senser bridge)				±0.5%		-50°C to 150°C	
 ¹⁾ Not included is the quantization noise of the DAC. The 11-bit DAC has a quantization noise of ± ½ LSB = 1.22 mV (5V VDD) = 0.025% 							
²⁾ Analog output range 2.5% to 95%.							

1.4. Analog Inputs versus Output Resolution

The RBic _{Lite}[™] incorporates an extended 14-bit charge-balanced ADC, which allows for a single gain setting on the pre-amplifier to handle bridge sensitivities from 1.2 to 36 mV/V while maintaining 8 to 12 bits of output resolution (default analog gain is 24). The tables below illustrate the minimum resolution achievable for a variety of bridge sensitivities. The yellow shadowed fields indicate that for these input spans with the selected analog gain setting, the quantization noise is higher than 0.1% FSO.

Table 1.10	ADC Resolution	Characteristics	for an	Analog	Gain o	of 6
------------	----------------	------------------------	--------	--------	--------	------

Analog Gain 6									
	Input Span [mV/V]		Allowed Offset	Minimum Guaranteed					
Min	Тур	Max	(+/- % of Span) ¹⁾	Resolution [Bits]					
57.3	80.0	105.8	38%	13.3					
50.6	70.0	92.6	53%	13.1					
43.4	60.0	79.4	73%	12.9					
36.1	50.0	66.1	101%	12.6					
28.9	40.0	52.9	142%	12.3					
21.7	30.0	39.7	212%	11.9					
¹⁾ In addition to Tco.	Tca		-	-					

Data Sheet May 25, 2011





 Table 1.11
 ADC Resolution Characteristics for an Analog Gain of 12

Analog Gain 12										
	Input Span [mV/V]		Allowed Offset	Minimum Guaranteed						
Min	Тур	Max	(+/- % of Span) ¹⁾	Resolution [Bits]						
43.3	60.0	79.3	3%	13.0						
36.1	50.0	66.1	17%	12.7						
25.3	35.0	46.3	53%	12.2						
18.0	25.0	33.0	101%	11.7						
14.5	20.0	26.45	142%	11.4						
7.2	10.0	13.22	351%	10.4						
3.6 ²⁾	5.0	6.6	767%	9.4						
¹⁾ In addition to Tco, T	¹⁾ In addition to Tco, Tcg									

²⁾ Yellow shadowing indicates that for these input spans with the selected analog gain setting, the quantization noise is > 0.1% FSO.

Table 1.12 ADC Resolution Characteristics for an Analog Gain of 24
--

Analog Gain 24										
	Input Span [mV/V]		Allowed Offset	Minimum Guaranteed						
Min	Тур	Max	(+/- % of Span) ¹⁾	Resolution [Bits]						
16	25.0	36	25%	12.6						
12.8	20.0	28.8	50%	12						
6.4	10.0	14.4	150%	11						
3.2	5.0	7.2	400%	10						
1.6 ²⁾	2.5	3.6	900%	9						
0.8 2)	1.2	1.7	2000%	8						
¹⁾ In addition to Tco.T										

²⁾ Yellow shadowing indicates that for these input spans with the selected analog gain setting, the quantization noise is > 0.1% FSO.





Table 1.13 ADC Resolution Characteristics for an Analog Gain of 48

Analog Gain 48							
	Input Span [mV/V]		Allowed Offset	Minimum Guaranteed			
Min	Тур	Мах	(+/- % of Span) ¹⁾	Resolution [Bits]			
10.8	15.0	19.8	3%	13			
7.2	10.0	13.2	35%	12.4			
4.3	6.0	7.9	100%	11.7			
2.9	4.0	5.3	190%	11.1			
1.8	2.5	3.3	350%	10.4			
1.0 ²⁾	1.4	1.85	675%	9.6			
0.72 2)	1.0	1.32	975%	9.1			
¹⁾ In addition to Tco,Tcg							

²⁾ Yellow shadowing indicates that for these input spans with the selected analog gain setting, the quantization noise is > 0.1% FSO.

ZSC31010 RBicLite[™] Low-Cost Sensor Signal Conditioner





Circuit Description 2

2.1. Signal Flow and Block Diagram

The RBicLite[™] series of resistive bridge sensor interface ICs were specifically designed as a cost-effective solution for sensing in building automation, industrial, office automation, and white goods applications. The RBicLite™ employs ZMDI's high precision bandgap with proportional-to-absolute temperature (PTAT) output; a low-power 14-bit analog-to-digital converter (ADC, A2D, A-to-D); and an on-chip DSP core with EEPROM to precisely calibrate the bridge output signal. Three selectable output modes, two analog and one digital, offer the ultimate in versatility across many applications.

The RBicLite[™] rail-to-rail ratiometric analog output Vout signal (0 to 5 V, Vout @ VDD = 5 V) suits most building automation and automotive requirements. Typical office automation and white goods applications require the 0 to 1 Vout signal, which in the RBic the [™] is referenced to the internal bandgap. Direct interfacing to P controllers is facilitated via ZMDI's single-wire serial ZACwire[™] digital interface.

The RBic_{life}™ is capable of running in high-voltage (5.5 to 30 V) systems when combined with an external JFET.



Figure 2.1 RBic_{Lite}™ ZSC31010 Block Diagram

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.

ZSC31010 RBicLite[™] Low-Cost Sensor Signal Conditioner





2.2. Analog Front End

2.2.1. Bandgap/PTAT and PTAT Amplifier

The highly-linear Bandgap/PTAT provides the PTAT signal to the ADC, which allows accurate temperature conversion. In addition, the ultra-low ppm-Bandgap provides a stable voltage reference over temperature for the operation of the rest of the IC.

The PTAT signal is amplified through a path in the pre-amplifier (PREAMP) and fed to the ADC for conversion. The most significant 12 bits of this converted result are used for temperature measurement and temperature correction of bridge readings. When temperature is output in Digital Mode, only the most significant 8 bits are given.

2.2.2. Bridge Supply

The voltage driven bridge is usually connected to V_{DD} and ground. As a power savings feature, the Bic_{Lite}^{TM} also includes a switched transistor to interrupt the bridge current via the Bsink pin. The transistor switching is synchronized to the A/D-conversion and released after finishing the conversion. To utilize this feature, the low supply of the bridge should be connected to Bsink instead of ground.

Depending on the programmable update rate, the average current consumption (including bridge current) can be reduced to approximately 20%, 5% or 1%.

2.2.3. PREAMP Block

The differential signal from the bridge is amplified through a chopper-stabilized instrumentation amplifier with very high input impedance, designed for low noise and low drift. This PREAMP provides gain for the differential signal and re-centers its DC to $V_{DD}/2$. The output of the PREAMP block is fed into the A/D-converter. The calibration sequence performed by the digital core includes an auto-zero sequence to null any drift in the PREAMP state over temperature.

The PREAMP is nominally set to a gain of 24. Other possible gain settings are 6, 12, and 48.

The inputs to the PREAMP from the VBN/VBP pins can be reversed via an EEPROM configuration bit.

2.2.4. Analog-to-Digital Converter (ADC)

A 14-bit/1 ms 2nd-order charge-balancing ADC is used to convert signals coming from the PREAMP. The converter, designed in full differential switched-capacitor technique, is used for converting the various signals to the digital domain. This principle offers the following advantages:

High noise immunity because of the differential signal path and integrating behavior Independent from clock frequency drift and clock jitter Fast conversion time owing to second order mode

Four selectable values for the zero point of the input voltage allow the conversion to adapt to the sensor's offset parameter. The conversion rate varies with the programmed update rate. The fastest conversion rate is 1 k samples/s; the response time is then 1 ms. Based on a best fit, the Integral Nonlinearity (INL) is $< 4 LSB_{14Bit}$.

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	15 of 16
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	15 01 40

RBic_{Lite}™ Low-Cost Sensor Signal Conditioner



(2)



2.3. Digital Signal Processor

A digital signal processor (DSP) is used for processing the converted bridge data as well as for performing temperature correction and for computing the temperature value for output on the digital channel.

The DSP reads correction coefficients from the EEPROM and can correct for

- Bridge Offset
- Bridge Gain
- Variation of Bridge Offset over Temperature (Tco)
- Variation of Bridge Gain over Temperature (Tcg)
- A Single Second Order Effect (SOT Second Order Term)

The EEPROM contains a single SOT that can be applied to correct one and only one of the following:

- 2nd order behavior of bridge measurement
- 2nd order behavior of Tco
- 2nd order behavior of Tcg

(For more details, see section 3.6.1.)

If the SOT applies to correcting the bridge reading, then the correction formula for the bridge reading is represented as a two step process as follows:

$$ZB = Gain \quad B(1 + \Delta T * Tcg) * (BR \quad Raw + Offset \quad B + \Delta T * Tco)$$
(1)

$$BR = ZB(1.25 + SOT * ZB)$$

- Where: **BR** = Corrected Bridge reading that is fed as digital or analog output on Sig[™] pin
 - **ZB** = Intermediate result in the calculations
 - **BR_Raw** = Raw Bridge reading from ADC
 - **T_Raw** = Raw Temperature reading converted from PTAT signal
 - **Gain_B** = Bridge gain term
 - Offset_B = Bridge offset term
 - **Tcg** = Temperature coefficient gain
 - **Tco** = Temperature coefficient offset
 - $\Delta T = (T_Raw T_{SETL})$
 - **T_Raw** = Raw Temperature reading converted from PTAT signal
 - T_{SETL} = Raw PTAT reference value (See ZSC31010_15_Tech_Notes_Cal_DLL_EXE_rev_X_xy.pdf for details.)
 - **SOT** = Second Order Term



Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	16 of 46
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	10 01 40

ZSC31010 RBicLite[™] Low-Cost Sensor Signal Conditioner





If the **SOT** applies to correcting the 2nd order behavior of **Tco**, then the formula for bridge correction is as follows:

$$BR = Gain _B(1 + \Delta T * Tcg) * [BR _Raw + Offset _B + \Delta T(SOT * \Delta T + Tco)]$$
(3)

Note: See section 3.6.2.7 for limitations when SOT applies to Tco.

If the SOT applies to correcting the 2nd order behavior of Tcg, then the formula for bridge correction is as follows:

$$BR = Gain B[1 + \Delta T(SOT * \Delta T + Tcg)] * [BR Raw + Offset B + \Delta T * Tco]$$
(4)

The bandgap reference gives a very linear PTAT signal, so temperature correction can always simply be accomplished with a linear gain and offset term.

Corrected Temp Reading:

$$T = Gain_T(T_Raw + Offset_T)$$
⁽⁵⁾

Where: **T_Raw** = Raw Temperature reading converted from PTAT signal

Offset_T = Temperature sensor offset coefficient

Gain_T = Temperature gain coefficient

2.3.1. EEPROM

The EEPROM contains the calibration coefficients for gain and offset, etc., and the configuration bits, such as output mode, update rate, etc. When programming the EEPROM, an internal charge-pump voltage is used, so a high voltage supply is not needed. The EEPROM is implemented as a shift register. During an EEPROM read, the contents are shifted 8 bits before each transmission of one byte occurs.

The charge-pump is internally regulated to 12.5 V, and the programming time is typically 6 ms.

Note: EEPROM writing can only be performed at temperatures lower than 85°C.

2.3.2. One-Wire Interface - ZACwire™

The IC communicates via a One-Wire Serial Interface (OWI, ZACwire™). There are different commands available for the following:

- Reading the conversion result of the ADC (Get_BR_Raw, Get_T_Raw)
- Calibration commands
- Reading from the EEPROM (dump of entire contents)
- Writing to the EEPROM (trim setting, configuration, and coefficients)

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	17 of 46
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	17 01 40



2.4. Output Stage

2.4.1. Digital to Analog Converter (Output DAC)

An 11-bit DAC, based on sub-ranging resistor strings, is used for the digital-to-analog output conversion in the analog ratiometric and absolute analog voltage modes. Selection during calibration configures the system to operate in either of these modes. The design allows for excellent testability as well as low power consumption.

Figure 2.2 shows the data timing of the DAC output with the 1 kHz update rate setting.

Figure 2.2 DAC Output Timing for Highest Update Rate



2.4.2. Output Buffer

A rail-to-rail operational amplifier (OpAmp) configured as a unity gain buffer can drive resistive loads (whether pull-up or pull-down) as low as 2.5 k Ω and capacitances up to 15 nF. To limit the error due to amplifier offset voltage, an error compensation circuit is included which tracks and reduces the offset voltage to < 1 mV.

2.4.3. Voltage Reference Block

A linear regulator control circuit is included in the Voltage Reference Block to interface with an external JFET to allow operation in systems where the supply voltage exceeds 5.5 V. This circuit can also be used for overvoltage protection. The regulator set point has a coarse adjustment via an EEPROM bit (see section 2.3.1), which can adjust the set point around 5.0 V or 5.5 V. In addition, the 1 V trim setting (see below) can also act as a fine adjustment for the regulation set point.

Note: If using the external JFET for over-voltage protection purposes (i.e., 5 V at JFET drain and expecting 5 V at JFET source), there will be a voltage drop across the JFET; therefore ratiometricity will be compromised somewhat depending on the rds(on) of the chosen JFET. A Vishay J107 is the best choice, because it has only an 8 mV drop worst case. If using as regulation instead of over-voltage, an MMBF4392 also works well.

The Voltage Reference Block uses the absolute reference voltage provided by the Bandgap to produce two regulated on-chip voltage references. A 1 V reference is used for the output DAC high reference, when the part is configured for 0 to 1 V analog output. For this reason, the 1 V reference must be very accurate and includes trim, such that its value can be trimmed within +/-3 mV of 1.0 V. The 1 V reference is also used as the on-chip reference for the JFET regulator block, so the regulation set point of the JFET regulator can be fine-tuned, using the 1 V trim. The 5 V reference can be trimmed within +/-15 mV. Table 2.1 shows the order of trim codes with 0111_B for the lowest reference voltage, and 1000_B for the highest reference voltage.

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	18 of 46
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	10 01 40

The Analog Mixed Signal Company





Table 2.1Order of Trim Codes

Order	1Vref/5Vreftrim3	1Vref/5Vref_trim2	1Vref/5Vref_trim1	1Vref/5Vref_trim0
Highest Reference Voltage	1	0	0	0
	1	0	0	1
	1	0	1	0
	1	0	1	1
	1	1	0	0
	1	1	0	1
	1	1	1	0
	1	1	1	1
	0	0	0	0
	0	0	0	1
	0	0	1	0
	0	0	1	1
	0	1	0	0
	0	1	0	1
	0	1	1	0
Lowest Reference Voltage	0	1	1	1

2.5. Clock Generator / Power-On Reset (CLKPOR)

If the power supply exceeds 2.5 V (maximum), the reset signal de-asserts, and the clock generator starts operating at a frequency of approximately 512 kHz (+17% / -22%). The exact value only influences the conversion cycle time and the communication to the outside world, but not the accuracy of signal processing. In addition, to minimize the oscillator error as the V_{DD} voltage changes, an on-chip regulator is used to supply the oscillator block.



2.5.1. Trimming the Oscillator

Trimming is performed at wafer level, and it is strongly recommended that this is not to be changed during calibration, because ZACwire[™] communication is no longer guaranteed at different oscillator frequencies.

Table 2.2 Oscillator Trimming

Trimming Bits	Delta Frequency (kHz)
100	+385
101	+235
110	+140
111	+65
000	Nominal
001	-40
010	-76
011	-110

Example: Programming $011_B \rightarrow$ the trimmed frequency = nominal value - 110 kHz.



Functional Description 3

3.1. **General Working Mode**

The command/data transfer takes place via the one-wire Sig™ pin, using the ZACwire™ serial communication protocol. After power-on, the IC waits for 6 ms (i.e., the command window) for the Start CM command. Without this command, the Normal Operation Mode (NOM) starts. In this mode, raw bridge values are converted, and the corrected values are presented on the output in analog or digital format (depending on the configuration stored in EEPROM).

Command Mode (CM) can only be entered during the 6 ms command window after power-on. If the IC receives the Start CM command during the command window, it remains in the Command Mode. The CM allows changing to one of the other modes via command. After command Start RM, the IC is in the Raw Mode (RM). Without correction, the raw values are transmitted to the digital output in a predefined order. The RM can only be stopped by power-off. Raw Mode is used by the calibration software for collection of raw bridge and temperature data, so the correction coefficients can be calculated.



Figure 3.1 General Working Mode

Data Sheet May 25, 2011	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	21 of 4
----------------------------	---	---------

The Analog Mixed Signal Company





3.2. ZACwire[™] Communication Interface

3.2.1. Properties and Parameters

Table 3.1 Pin Configuration and Latch-Up Conditions

No.	Parameter	Symbol	Min	Тур	Max	Unit	Comments
1	Pull-up resistor (on-chip)	R _{ZAC,pu}		30		kΩ	On-chip pull-up resistor switched on during Digital Output Mode and during CM Mode (first 6 ms after power up)
2	Pull-up resistor (external)	R _{ZAC,pu_ext}	150			Ω	If the master communicates via a push-pull stage, no pull-up resistor is needed; otherwise, a pull-up resistor with a value of at least 150 Ω must be connected.
3	ZACwire™ rise time	$T_{ZAC,rise}$			5	μs	Any user RC network included in Sig™ path must meet this rise time
4	ZACwire [™] line resistance ¹⁾	R _{ZAC,line}			3.9	kΩ	Also see Table 1.8
5	ZACwire [™] load capacitance ¹⁾	C _{ZAC,load}	0	1	15	nF	Also see Table 1.8
6	Voltage low level	V _{ZAC,low}		0	0.2	V_{DD}	Rail-to-rail CMOS driver
7	Voltage high level	$V_{ZAC,high}$	0.8	1		V_{DD}	Rail-to-rail CMOS driver
1)) The rise time must be $T_{ZAC,rise} = 2 * R_{ZAC,line} * C_{ZACload} \le 5 \ \mu s$. If using a pull-up resistor instead of a line resistor, it must meet this specification.						

3.2.2. Bit Encoding

Figure 3.2 Manchester Duty Cycle



Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	22 of 46
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	22 01 40



3.2.3. Write Operation from Master to RBic_{Lite}™

The calibration master sends a 19-bit packet frame to the IC.

Figure 3.3 19-Bit Write Frame



The incoming serial signal will be sampled at a 512 kHz clock rate. This protocol is very tolerant to clock skew, and can easily tolerate baud rates in the 6 kHz to 48 kHz range.

3.2.4. RBIC_{Lite}™ Read Operations

The incoming frame will be checked for proper parity on both, command and data bytes, as well as for any edge time-outs prior to a full frame being received.

Once a command/data pair is received, the $RBic_{Lite}$ TM will perform that command. After the command has been successfully executed by the IC, the IC will acknowledge success by a transmission of an A5_H-byte back to the master. If the master does not receive an A5_H transmission within 130 ms of issuing the command, it must assume the command was either improperly received or could not be executed.





Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	22 of 16
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	23 01 40



The RBic_{Lite}[™] transmits 10-bit bytes (1 start bit, 8 data bits, 1 parity bit). During calibration and configuration, transmissions are normally either A5_H or data. A5_H indicates successful completion of a command. There are two different digital output modes configurable (digital output with temperature, and digital output with only bridge data). During Normal Operation Mode, if the part is configured for digital output of the bridge reading, it first transmits the high byte of bridge data, followed by the low byte. The bridge data is 14 bits in resolution, so the upper two bits of the high byte are always zero-padded. There is a 32 µs stop time when the bus is held high between bytes in a packet.





The second digital output mode is digital output bridge reading with temperature. It will be transmitted as a 3-databyte packet. The temperature byte represents an 8-bit temperature quantity, spanning from -50 to 150°C.

Figure 3.6 Digital Output (NOM) Bridge Readings with Temperature



The EEPROM transmission occurs in a packet with 14 data bytes, as shown below.

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	24 of 46
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	24 01 40



Figure 3.7 Read EEPROM Contents



There is a variable idle time between packets, which varies with the update rate setting in the EEPROM.

Figure 3.8 Transmission of a Number of Data Packets



The table below shows the idle time between packets versus the update rate. This idle time can vary by nominal +/-15% between parts, and over a temperature range of -50 to 150°C.

Transmissions from the IC occur at one of two speeds depending on the update rate programmed in EEPROM. If the user chooses one of the two fastest update rates (1 ms or 5 ms) then the baud rate of the digital transmission will be 32 kHz (minimum 25 kHz). If, however, the user chooses one of the two slower update rates (25 ms or 125 ms), then the baud rate of the digital transmission will be 8 kHz (maximum 9.4 kHz).

The total transmission time for both digital output configurations is shown in Table 3.2.

Table 3.2 Total Transmission Time for Different Update Rate Settings and Output Configura	ation
---	-------

Update Rate	Baud Rate*	Idle Time	Transmission Time – Bridge Only Readings			Tran Bridge &	smission Ti Femperature	me – Readings
1 ms (1 kHz)	32 kHz	1.0 ms	20.5 bits	31.30 µs	1.64 ms	31.0 bits	31.30 µs	1.97 ms
5 ms (200 Hz)	32 kHz	4.85 ms	20.5 bits	31.30 µs	5.49 ms	31.0 bits	31.30 µs	5.82 ms
25 ms (40 Hz)	8 kHz	22.5 ms	20.5 bits	125.00 µs	25.06 ms	31.0 bits	125.00 µs	26.38 ms
125 ms (8 Hz)	8 kHz	118.0 ms	20.5 bits	125.00 µs	<mark>120.56 ms</mark>	31.0 bits	125.00 µs	121.88 ms
* Typical values. Minimum baud rate for 1 ms or 5 ms: 26kHz; maximum baud rate for 25 ms or 125 ms: 9.4kHz.								

RBicLite[™] Low-Cost Sensor Signal Conditioner





The temperature raw reading is performed less often than a bridge reading, because the temperature changes more slowly.

Table 3.3 shows the timing for the special measurements (temperature and bridge measurement) in the different update rate modes.

Table 3.3 Special Measurement versus Update Rate

Update Rate Setting	Special Measurement
00	Every 128 bridge measurements
01	Every 64 bridge measurements
10	Every 16 bridge measurements
11	Every 8 bridge measurements

It is easy to program any standard microcontroller to communicate with the RBic_{Lite}™. ZMDI can provide sample code for a MicroChip PIC microcontroller.

For update rates less than 1 kHz, the output is followed by a power-down, as shown below.

Figure 3.9 ZACwire[™] Output Timing for Lower Update Rates



3.2.5. High Level Protocol

The RBic_{Lite}[™] will listen for a command/data pair to be transmitted for the 6 ms after the de-assertion of its internal Power-On Reset (POR). If a transmission is not received within this time frame, then it will transition to Normal Operation Mode (NOM). In NOM, it will output bridge data in 0 to 1 V analog, rail-to-rail ratiometric analog output, or digital output, depending on how the part is currently configured.

If the RBic_{Lite}[™] receives a Start CM command within the first 6 ms after the de-assertion of POR, then it will go into Command Mode (CM). In this mode, calibration/configuration commands will be executed. The RBic_{Lite}[™] will acknowledge successful execution of commands by transmission of an A5_H. The calibrating/ configuring master will know that a command was not successfully executed if no response is received after 130 ms of issuing the command. Once in command interpreting/executing mode, the RBic_{Lite}[™] will stay in this mode until power is removed, or a Start NOM (Start Normal Operation Mode) command is received. The Start CM command is used as an interlock mechanism, to prevent a spurious entry into command mode on power-up. The first command received within the 6 ms window of POR must be a Start CM command to enter into command interpreting mode. Any other commands will be ignored.

Data Sheet May 25, 2011	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	26 of 46
----------------------------	---	----------





3.3. Command/Data Bytes Encoding

The 16-bit command/data stream sent to the RBic_{Lite}[™] can be broken into 2 bytes, shown in Table 3.4. The most significant byte encodes the command byte. The least significant byte represents the data byte.

Table 3.4	Command/Data	Bytes	Encoding
-----------	--------------	--------------	----------

Command Byte	Data Byte	Description				
00 _H	XX _H	Read EEPROM command via Sig [™] pin; for more details, refer to section 3.7.				
20 _H	5X _H	Enter Test Mode (subset of Command Mode for test purposes only): Sig [™] pin will assume the value of different internal test points depending on the most significant nibble of data sent. DAC Ramp Test Mode. Gain_B[13:3] contains the starting point, and the increment is (Offset_B/8). The increment will be added every 125 µsec.				
30 _н	dd _H	rim/Configure: higher nibble of data byte determines what is trimmed/configured. Lower nibble is lata to be programmed. See Table 3.5 for configuration details of data byte $dd_{\rm H}$.				
	00 _H	Start NOM => Ends Command Mode, transition to Normal Operation Mode				
40H	10 _H	Start Raw Mode (RM)				
		In this mode, if Gain_B = 800_H and Gain_T = 80_H , then the digital output will simply be the raw values of the ADC for the Bridge reading and the PTAT conversion.				
50 _H	XX _H	Start_CM => Start the Command Mode; used to enter command interpret mode				
60 _H	dd _H	Program SOT (2 nd order term)				
70 _H	dd _H	Program T _{SETL}				
80 _H	dd _H	Program Gain_B, upper 7 bits (set MSB of dd_{H} to 0_{B})				
90 _H	dd _H	Program Gain_B, lower 8 bits				
A0 _H	dd _H	Program Offset_B, upper 6 bits (set the two MSBs of dd_{H} to 00_{B})				
B0 _H	dd _H	Program Offset_B, lower 8 bits				
C0 _H	dd _H	Program Gain_T				
D0 _H	dd _H	Program Offset_T				
E0 _H	dd _H	Program Tco				
F0 _H	dd _H	Program Tcg				

Table 3.5 Programming Details for Command 30_H

3 rd Nibble	4 th Nibble	Description
0 _H	Xbbb _B	Trim oscillator; only least significant 3 bits of data used (Xbbb _B).
1 _H	bbbb _B	Trim 1 V reference; least significant 4 bits of data used (<i>bbbb</i> _B).
2 _H	XXbb _B	Offset Mode; only least significant 2 bits of data used (XXbb _B).
3 _H	XXbb _B	Set output mode; only least significant 2 bits of data used (XXbb _B).
4 _H	XXbb _B	Set update rate; only least significant 2 bits of data used (XXbb _B).
5 _H	bbbb _B	Configure JFET regulation
6 _H	bbbb _B	Program the Tc_cfg register.
7 _H	bbbb _B	Program bits [99:96] of EEPROM. (SOT_cfg, Pamp_Gain)





3.4. Calibration Sequence

Although the RBic_{Lite}[™] can function with many different types of resistive bridges, assume it is connected to a pressure bridge for the following calibration example.

In this case, calibration essentially involves collecting raw bridge and temperature data from the Bic_{Lite}^{TM} for different known pressures and temperatures. This raw data can then be processed by the calibration master (the PC), and the calculated coefficients can then be written to the EEPROM of the Bic_{Lite}^{TM} .

ZMDI can provide software and hardware with samples to perform the calibration.

There are three main steps to calibration:

- Assigning a unique identification to the IC. This identification is programmed into the EEPROM and can be used as an index into the database stored on the calibration PC. This database will contain all the raw values of bridge readings and temperature reading for that part, as well as the known pressure and temperature the bridge was exposed to. This unique identification can be stored in a combination of the following EEPROM registers: T_{SETL}, Tcg, Tco. These registers will be overwritten at the end of the calibration process, so this unique identification is not a permanent serial number.
- 2. Data collection. Data collection involves getting raw data from the bridge at different known pressures and temperatures. This data is then stored on the calibration PC using the unique identification of the IC as the index to the database.
- 3. Coefficient calculation and write. Once enough data points have been collected to calculate all the desired coefficients, then the coefficients can be calculated by the calibrating PC and written to the IC.

Step 1: Assigning Unique Identification

Assigning a unique identification number is as simple as using the commands Program T_{SETL} , Program Tcg, and Program Tco. These three 8-bit registers will allow for 16M unique devices. In addition, Gain_B must be programmed to 800_{H} (unity), and Gain_T must be programmed to 80_{H} (unity).

Step 2: Data Collection

The number of different unique (pressure, temperature) points that calibration needs to be performed at depends on the customer's needs. The minimum is a 2-point calibration, and the maximum is a 5-point calibration. To acquire raw data from the part, instruct the $RBic_{Lite}$ TM to enter Raw Mode. This is done by issuing a Start_CM (Start Command Mode, 5000_H) command to the IC, followed by a Start_RM (Start Raw Mode, 4010_H) command with the LSB of the upper data nibble set. Now, if the Gain_B term was set to unity (800_H) and the Gain_T term was also set to unity (80_H), then the part will be in Raw Mode and will be outputting raw data on its SigTM pin, instead of corrected bridge and temperature values. The calibration system should now collect several of these data points (16 each of bridge and temperature is recommended) and average them. These raw bridge and temperature measurements should be stored in the database, along with the known pressure and temperature. The output format during Raw Mode is Bridge_High, Bridge_Low, Temp, each of these being 8-bit quantities. The upper 2 bits of Bridge_High are zero-filled. The Temp data (8-bit only) would not really be enough data for accurate temperature calibration. Therefore, the upper 3 bits of temperature information are not given, but rather assumed known. Therefore, effectively 11 bits of temperature information are provided in this mode.

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	28 of 46
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	20 01 10



Step 3: Coefficient Calculations

The math to perform the coefficient calculation is very complicated and will not be discussed in detail here. There is a rough overview in section 3.6. Instead ZMDI will provide software to perform the coefficient calculation. ZMDI can also provide source code of the algorithms in a C-code format. Once the coefficients are calculated, the final step is to write them to the EEPROM of the RBic_{Lite}TM.

The number of calibration points required can be as few as two or as many as five. This depends on the precision desired, and the behavior of the resistive bridge in use.

- 2-point calibration would be used to obtain only a gain and offset term for bridge compensation with no temperature compensation for either term.
- 3-point calibration would be used to also obtain the Tco term for 1st order temperature compensation of the bridge offset term.
- 3-point calibration could also be used to obtain the additional term SOT for 2nd order correction for the bridge (SOT_BR), but no temperature compensation of the bridge output; see section 3.6.2.7 for limitations.
- 4-point calibration would be used to also obtain both, the Tco term and the Tcg term, which provides 1st order temperature compensation of the bridge offset gain term.
- 4-point calibration could also be used to obtain the Tco term and the SOT_BR term; see section 3.6.2.7 for limitations.
- 5-point calibration would be used to obtain Tco, Tcg, and an SOT term that provides 2nd order correction applied to one and only one of the following: 2nd order Tco (SOT_Tco), 2nd order Tcg (SOT_Tcg), or 2nd order bridge (SOT_BR); see section 3.6.2.7 for limitations.





3.5. EEPROM Bits

Table 3.6 shows the bit order in the EEPROM, which are programmed through the serial interface. See Table 5.1 for the ZSC31010 default settings.

Table 3.6 ZSC31010 EEPROM Bits

Description	NOTES
Osc_Trim	See the table in section 2.5.1 for complete data.
	100 => Fastest
	101 => 3 clicks faster than nominal
	110 => 2 clicks faster than nominal
	111 => 1 click faster than nominal
	000 => Nominal
	001 => 1 click slower than nominal
	010 => 2 clicks slower than nominal
	011 => Slowest
1V_Trim/JFET_Trim	See the table in section 2.4.3.
A2D_Offset	Offset selection:
	11 => [-1/2, 1/2] mode bridge inputs
	10 => [-1/4, 3/4] mode bridge inputs
	01 => [-1/8,7/8] mode bridge inputs
	00 => [-1/16,15/16] mode bridge inputs
	To change the bridge signal polarity, set Tc_cfg[3](=Bit 87).
Output_Select	00 => Digital (3-bytes with parity):
	Bridge High {00,[5:0]}
	Bridge Low [7:0]
	Temp [7:0]
	01 => 0-1 V Analog
	10 => Rail-to-rail ratiometric analog output
	11 => Digital (2-bytes with parity) (No Temp)
	Bridge High {00,[5:0]}
	Bridge Low [7:0]
Update_Rate	00 => 1 msec (1 kHz)
	01 => 5 msec (200 Hz)
	10 => 25 msec (40 Hz)
	11 => 125 msec (8 Hz)
JFET_Cfg	00 => No JFET regulation (lower power)
	01 => No JFET regulation (lower power)
	10 => JFET regulation centered around 5.0 V
	11 => JFET regulation centered around 5.5 V (i.e. over-voltage protection).
	Osc_Trim 1V_Trim/JFET_Trim A2D_Offset Output_Select Update_Rate JFET_Cfg

Data Sheet May 25, 2011	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	30 of 46
----------------------------	---	----------

RBic_{Lite}™ Low-Cost Sensor Signal Conditioner





EEPROM Range	Description	Notes
29:15	Gain_B	Bridge Gain: Gain_B[14] => multiply x 8 Gain_B[13:0] => 14-bit unsigned number representing a number in the range [0,8)
43:30	Offset_B	Signed 14-bit offset for bridge correction
51:44	Gain_T	Temperature gain coefficient used to correct PTAT reading.
59:52	Offset_T	Temperature offset coefficient used to correct PTAT reading.
67:60	T _{SETL}	Raw PTAT reference value. (See ZSC31010_15_Tech_Notes_ Cal_DLL_EXE_rev_X_xy.pdf for details.)
75:68	Тсд	Coefficient for temperature correction of bridge gain term. Tcg = 8-bit magnitude of Tcg term. Sign is determined by Tc_cfg (bits 87:84).
83:76	Тсо	Coefficient for temperature correction of bridge offset term. Tco = 8-bit magnitude of Tco term. Sign and scaling are determined by Tc_cfg (bits 87:84).
87:84	Tc_cfg	This 4-bit term determines options for temperature compensation of the bridge: Tc_cfg[3] => If set, bridge signal polarity flips. Tc_cfg[2] => If set, Tcg is negative. Tc_cfg[1] => Scale magnitude of Tco term by 8, and if SOT applies to Tco, scale SOT by 8. Tc_cfg[0] => If set, Tco is negative.
95:88	SOT	2^{nd} Order Term. This term is a 7-bit magnitude with sign. SOT[7] = 1 → negative SOT[7] = 0 → positive SOT[6:0] = magnitude [0-127] This term can apply to a 2^{nd} order Tcg, Tco or bridge correction [‡] . (See Tc_cfg above.)

[‡] The SOT range for the bridge correction is limited for the negative value to 0xC0 by the MathLib.DLL.





EEPROM Range	Description	Notes
99:96	{SOT_cfg,	Bits [99:98] = SOT_cfg (For more details, see section 3.6.1.)
	Pamp_Gain}	00 = SOT applies to Bridge
		01 = SOT applies to Tcg
		10 = SOT applies to Tco
		11 = Prohibited
		Bits [97:96] = PreAmp Gain
		00 => 6
		01 => 24 (default setting)
		10 => 12
		11 => 48
		(Only the default gain setting (24) is tested at the factory; all other gain settings are not guaranteed.)

3.6. Calibration Math

3.6.1. Correction Coefficients

All terms are calculated external to the IC and then programmed to the EEPROM through the serial interface.

Table 3.7 Correction Coefficient

Coefficient	Description
Gain_B	Gain term used to compensate span of Bridge reading
Offset_B	Offset term used to compensate offset of Bridge reading
Gain_T	Gain term used to compensate span of Temp reading
Offset_T	Offset term used to compensate offset of Temp reading
SOT	 Second Order Term. The SOT can be applied as a second order correction term for the following: Bridge measurement Temperature coefficient of offset (Tco) Temperature coefficient of gain (Tcg) The EEPROM bits 99:98 determine what SOT applies to. Note: There are limitations for the SOT for the bridge measurement and for the SOT for the Tco, which are explained in section 3.6.2.7.
T _{SETL}	RAW PTAT reference value. (See ZSC31010_15_Tech_Notes_Cal_DLL_EXE_rev_X_xy.pdf for details.)
Тсд	Temperature correction coefficient of bridge gain term (this term has an 8-bit magnitude and a sign bit (Tc_cfg[2]).
Тсо	Temperature correction coefficient of bridge offset term (this term has an 8-bit magnitude, a sign bit $(Tc cfg[0])$, and a scaling bit $(Tc cfg[1])$, which can multiply its magnitude by 8).





3.6.2. Interpretation of Binary Numbers for Correction Coefficients

BR_Raw should be interpreted as an unsigned number in the set [0, 16383] with a resolution of 1.

T_Raw should be interpreted as an unsigned number in the set [0, 16383], with a resolution of 4.

3.6.2.1. Gain_B Interpretation

Gain_B should be interpreted as a number in the set [0, 64]. The MSB (bit 14) is a scaling bit that will multiply the effect of the remaining bits Gain_B[13:0] by 8. Bits Gain_B[13:0] represent a number in the range of [0, 8], with Gain_B[13] having a weighting of 4, and each subsequent bit has a weighting of $\frac{1}{2}$ the previous bit.

Table 3.8 Gain_B[13:0] Weightings

Bit Position	Weighting
13	$2^2 = 4$
12	2 ¹ = 2
11	$2^0 = 1$
10	2 ⁻¹
3	2 ⁻⁸
2	2 ⁻⁹
1	2 ⁻¹⁰
0	2 ⁻¹¹

Examples:

The binary number: $010010100110001_B = 4.6489$; Gain_B[14] is 0_B , so the number represented by Gain_B[13:0] is not multiplied by 8.

The binary number: $101100010010110_B = 24.586$; Gain_B[14] is 1_B , so the number represented by Gain_B[13:0] is multiplied by 8.

Limitation: Using the 5-point calibration 5pt-Tcg&Tco&SOT_Tco (including the second order SOT_Tco), the Gain_B is limited to a value equal or less than 8 (instead of 64).





3.6.2.2. Offset_B Interpretation

Offset_B is a 14-bit signed binary number in two's complement form. The MSB has a weighting of -8192. The following bits then have a weighting of 4096, 2048, 1024, ...

Table 3.9 Offset_B Weightings

Bit Position	Weighting
13	-8192
12	2 ¹² = 4096
11	2 ¹¹ = 2048
10	2 ¹⁰ = 1024
3	$2^3 = 8$
2	$2^2 = 4$
1	2 ¹ = 2
0	2 ⁰ = 1

For example, the binary number $111111111100_B = -4$

3.6.2.3. Gain_T Interpretation

Gain_T should be interpreted as a number in the set [0,2]. Gain_T[7] has a weighting of 1, and each subsequent bit has a weighting of 1/2 the previous bit.

Bit Position	Weighting
7	$2^0 = 1$
6	2-1
5	2-2
4	2 ⁻³
3	2-4
2	2 ⁻⁵
1	2 ⁻⁶
0	2-7

Table 3.10 Gain_T Weightings



3.6.2.4. Offset_T Interpretation

Offset_T is an 8-bit signed binary number in two's complement form. The MSB has a weighting of -128. The following bits then have a weighting of 64, 32, 16 ...

Table 3.11 Offset_T Weightings

Bit Position	Weighting
7	-128
6	$2^6 = 64$
5	2 ⁵ = 32
4	2 ⁴ = 16
3	$2^3 = 8$
2	$2^2 = 4$
1	2 ¹ = 2
0	2 ⁰ = 1

For example, the binary number $00101001_B = 41$.

3.6.2.5. Tco Interpretation

Tco is specified as an 8-bit magnitude with an additional sign bit (Tc_cfg[0]), and a scalar bit (Tc_cfg[1]). When the scalar bit is set, the signed Tco is multiplied by 8.

Tco Resolution:	0.175 μV/V/ºC	(input referred)
Tco Range:	± 44.6 µV/V/°C	(input referred)

If the scaling bit is used, then the above resolution and range are scaled by 8 to give the following results:

Tco Scaled Resolution:	1.40 µV/V/ºC	(input referred)
Tco Scaled Range:	± 357 μV/V/ºC	(input referred)

3.6.2.6. Tcg Interpretation

Tcg is specified as an 8-bit magnitude with an additional sign bit (Tc_cfg[2]).

Tcg Resolution: 17.0 ppm/°C Tcg Range: ±4335 ppm/°C

3.6.2.7. SOT Interpretation

SOT is a 2nd order term that can apply to one and only one of the following: bridge non-linearity correction, Tco non-linearity correction, or Tcg non-linearity correction.

As it applies to bridge non-linearity correction:

Resolution: 0.25% @ Full Scale

```
2^{nd} order correction SOT_BR is possible up to +5%/-6.2% full scale difference from the ideal fit (straight line), because the SOT coefficient values are limited to the range of (0xC0 = -0.25<sub>dec</sub>) to (0x7F = 0.4960938<sub>dec</sub>). (Saturation in internal arithmetic will occur at greater negative non-linearities.)
```

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	25 of 16
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	55 01 40



Limitation: Using any calibration method for which SOT is applied to the bridge measurement (SOT_BR), there is a possibility of calibration math overflow. This only occurs if the sensor input exceeds 200% of the calibrated full span, which means the highest applied sensor input should never go higher than this value.

Example: This example of the limitation when SOT is applied to the bridge reading uses a pressure sensor bridge that outputs -10 mV at the lowest pressure of interest. That point is calibrated to read 0%. The same sensor outputs +40 mV at the highest pressure of interest. That point is calibrated to read 100%. This sensor has a 50 mV span over the pressure range of interest. If the sensor were to experience an over-pressure event that took the sensor output up to 90 mV (200% of span), the internal calculations could overflow. The result would be a corrected bridge reading that would not be saturated at 100% as expected, but instead read a value lower than 100%. This problem only occurs when SOT is applied to correct the bridge reading.

As SOT applies to Tcg:

As it applies to Tco:

Two settings are possible. It is possible to scale the effect of SOT by 8. If Tc_cfg[1] is set, then both, Tco and SOT's contribution to Tco, are multiplied by 8.

Resolution at unity scaling:	1.51 nV/V/(°C) ²	(input referred)
Range:	±0.192 μV/V/(°C) ²	(input referred)
Resolution at 8x scaling:	12.1 nV/V/(°C) ²	(input referred)
Range:	±1.54 μV/V/(°C) ²	(input referred)

Limitation: If the second order term SOT applies to Tco, the bridge gain Gain_B is limited to values equal or less than 8 (instead of 64).



Reading EEPROM Contents 3.7.

The contents of the entire EEPROM memory can be read using the Read EEPROM command (00_H). This command causes the IC to output consecutive bytes on the ZACwire™. After each transmission, the EEPROM contents are shifted by 8 bits. The bit order of these bytes is given in Table 3.12.

Table 3.12 EEPROM Read Order

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Byte 1				Offset_	_B[7:0]				
Byte 2	Gain_	T[1:0]		<u> </u>	Offset_	B[13:8]			
Byte 3	Offset	_T[1:0]		ļ	Gain_	T[7:2]			
Byte 4	T _{SETI}	_[1:0]			Offset_	_T[7:2]			
Byte 5	Tcg	[1:0]			T _{SETI}	[7:2]			
Byte 6	Тсо	[1:0]			Tcg	[7:2]			
Byte 7	Tc_cf	g[1:0]			Тсо	[7:2]			
Byte 8	sc		SOT	[5:0]			Tc_cf	g[3:2]	
Byte 9	Osc_T	rim[1:0]		SOT_cf	g[3:0] *		SOT	SOT[7:6]	
Byte 10	Output_ Select[0]	A2D_Of	fset[1:0]		1V_Trin	n[3:0] **		Osc_Trim[2]	
Byte 11		Gain_B[2:0]		JFET_(Cfg[1:0]	Update_I	Rate[1:0]	Output_ Select[1]	
Byte 12	Gain_B[10:3]								
Byte 13	Offset_B[3:0] *** Gain_B[14:11]								
Byte 14	A5 _H								
* SOT_cfg/Pamp_Gain ** 1V_Trim/JFET_Trim *** Duplicates first 4 bits of Byte 1									

Data Sheet May 25, 2011

© 2011 Zentrum Mikroelektronik Dresden AG - Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.





4 Application Circuit Examples

Note: The typical output analog load resistor $R_L = 10 \text{ k}\Omega$ (minimum 2.5 k Ω). This optional load resistor can be configured as a pull-up or pull-down. If it is configured as a pull-down, it cannot be part of the module to be calibrated because this would prevent proper operation of the ZACwireTM. If a pull-down load is desired, it must be added to the system after module calibration.

There is no output load capacitance needed.

EEPROM contents: OUTPUT_select, JFET_Cfg, 1V_Trim/JFET-Trim

4.1. Three-Wire Rail-to-Rail Ratiometric Output

This example shows an application circuit for rail-to-rail ratiometric voltage output configuration with temperature compensation via internal PTAT. The same circuitry is applicable for a 0 to 1 V absolute analog output.

Figure 4.1 Rail-to-Rail Ratiometric Voltage Output



The optional bridge sink allows power savings switching off the bridge current. The output voltage can be one of the following options:

- Rail-to-rail ratiometric analog output V_{DD} (= V_{supply}).
- 0 to 1 V absolute analog output. The absolute voltage output reference is trimmable 1 V (±3 mV) in the 1 V output mode via a 4-bit EEPROM field (see section 2.4.3).



4.2. Absolute Analog Voltage Output

The figure below shows an application circuit for an absolute voltage output configuration with temperature compensation via internal temperature PTAT, and external JFET regulation for all industry standard applications. The gate-source cutoff voltage (V_{GS}) of the selected JFET must be ≤ -2 V.

Figure 4.2 Absolute Analog Voltage Output



The output signal range can be one of the following options:

- 0 to 1 V analog output. The absolute voltage output reference is trimmable: 1 V (± 3 mV) in the 1 V output mode via a 4-bit EEPROM field (see section 2.4.3).
- Rail-to-rail analog output. The on-chip reference for the JFET regulator block is trimmable: 5 V (± 15 mV) in the ratiometric output mode via a 4-bit EEPROM field (see section 2.4.3).



4.3. Three-Wire Ratiometric Output with Over-Voltage Protection

The figure below shows an application circuit for a ratiometric output configuration with temperature compensation via an internal diode.



Figure 4.3 Ratiometric Output, Temperature Compensation via Internal Diode

In this application, the JFET is used for over-voltage protection. JFET_Cfg bits [14:13] in EEPROM are configured to 5.5 V. There is an additional maximum error of 8 mV caused by the non-zero r_{ON} of the limiter JFET.



4.4. Digital Output

For all three circuits, the output signal can also be digital. Depending on the output select bits, the bridge signal, or the bridge signal and temperature signal are sent.

For the digital output, no load resistor or load capacity are necessary. No pull-down resistor is allowed. If a line resistor or pull-up resistor is used, the requirement for the rise time must be met ($\leq 5 \ \mu$ s). The IC output includes a pull-up resistor of about 30 k Ω . The digital output can easily be read by firmware from a microcontroller, and ZMDI can provide the customer with software in developing the interface.

4.5. Output Short Protection

The output of the RBic_{Lite}TM has no short protection. Therefore, a resistor R_{SP} in series with the output must be added in the application module. Refer to Table 4.1 to determine the value of $R_{SP}^{\$}$.

To minimize additional error caused by this resistor for the analog output voltage, the load impedance must meet the following requirement:

 $R_L >> R_{SP}$

Table 4.1 Resistor Values for Short Protection

Temperature Range (T _{AMBMAX})	Resistor R _{SP}	Note
Up to 85°C	51 Ω	
Up to125°C	100 Ω	R _{SP} = V _{DD} /I _{max} with I _{max} = ([(170°C - T _{AMBMAX})/(163°C/W)] - V _{DD} * I _{DD})/VDD
Up to 150°C	240 Ω	

© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.

 $^{^{\$}}$ Tested at V_{DD} =5V for 20 minutes for T_AMBMAX





5 Default EEPROM Settings

If needed, the default setting for the ZSC31010 can be reprogrammed as described in section 3.

Table 5.1 Factory Settings for the ZSC31010 EEPROM

EEPROM Range	Name	Default Values (Hex) Until Week 9/2006	Default Values (Hex) Since Week 10/2006	Default Values (Hex) Since Week 48/2008
2:0	Osc_Trim	0xX	0xX	0xX
6:3	1V_Trim/JFET_Trim	0xX	0xX	0xX
8:7	A2D_Offset	0x0	0x3	0x3
10:9	Output_Select	0x3	0x2	0x2
12:11	Update_Rate	0x2	0x1	0x1
14:13	JFET_Cfg	0x1	0x2	0x2
29:15	Gain_B	0x800	0x0	0x3FFF
43:30	Offset_B	0x0	0x203	0x00FF
51:44	Gain_T	0x80	0x80	0x80
59:52	Offset_T	0x0	0x0	0x0
67:60	T	0x0	0x0	0x0
75:68	Тсд	0x0	0x0	0x0
83:76	Тсо	0xE	0x0	0x0
87:84	Tc_cfg	0x0	0x0	0x0
95:88	SOT	0x0	0x0	0x0
99:96	{SOT_cfg, Pamp_Gain}	0x1	0x5	0x5

© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.





6 Pin Configuration and Package

The standard package of the RBic_{Lite}™ is an SOP-8 (3.81 mm / 150 mil body) with a lead-pitch 1.27 mm / 50 mil.

Table 6.1 Storage and Soldering Conditions for the SOP-8 Package

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Maximum Storage Temperature	T _{max_storage}	Less than 10hrs, before mounting			150	°C
Minimum Storage Temperature	T _{min_storage}	Store in original packing only	-50			°C
Maximum Dry-Bake Temperature	T _{drybake}	Less than100 hrs total, before mounting			125	°C
Soldering Peak Temperature	T _{peak}	Less than 30s (IPC/JEDEC-STD-020 Standard)			260	°C

Figure 6.1 RBic_{Lite}™ Pin-Out Diagram



Table 6.2 RBic_{Lite}™ Pin Configuration

Pin No.	Name	Description
1	Bsink	Optional ground connection for bridge ground. Used for power savings.
2	VBP	Positive bridge connection
3	N/C	No connection
4	VBN	Negative bridge connection
5	Vgate	Gate control for external JFET regulation/over-voltage protection
6	VDD	Supply voltage (2.7 - 5.5 V)
7	SIG™	ZACwire™ interface (analog out, digital out, calibration interface)
8	VSS	Ground supply

Data Sheet May 25, 2011	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	43 of 46
----------------------------	---	----------

ZSC31010 RBicLite[™] Low-Cost Sensor Signal Conditioner





7 ESD/Latch-Up-Protection

All pins have an ESD protection of > 4000 V and a latch-up protection of \pm 100 mA or of +8V/-4 V (to VSS/VSSA). ESD protection referred to the Human Body Model is tested with devices in SOP-8 packages during product qualification. The ESD test follows the Human Body Model with 1.5 k Ω /100 pF based on MIL 883, Method 3015.7.

8 Test

The test program is based on this datasheet. The final parameters that will be tested during series production are listed in the tables of section 1. The digital part of the IC includes a scan path, which can be activated and controlled during wafer test. It guarantees failure coverage of more than 98%. Further test support for testing of the analog parts on wafer level is included in the DSP.

9 Quality and Reliability

The RBic_{Lite}[™] has successfully passed AEC Q100 automotive qualification testing, which includes reliability testing for the temperature range from -50 to 150°C.^{**}

10 Customization

For high-volume applications which require an upgraded or downgraded functionality compared to the ZSC31010, ZMDI can customize the circuit design by adding or removing certain functional blocks. ZMDI can provide a custom solution quickly because it has a considerable library of sensor-dedicated circuitry blocks. Please contact ZMDI for further information.

11 Ordering Examples

Sales Code	Description	Package
ZSC31010CEB	ZSC31010 RBic _{Lite} ™ Die — Temperature range:-50°C to +150°C	Unsawn on Wafer
ZSC31010CEC	ZSC31010 RBic _{Lite} ™ Die — Temperature range:-50°C to +150°C	Sawn on Wafer Frame
ZSC31010CED	ZSC31010 RBic _{Lite} ™ Die — Temperature range:-50°C to +150°C	Waffle Pack
ZSC31010CEG1	ZSC31010 RBic _{Lite} ™ SOP8 (150 mil) — Temperature range:-50°C to +150°C	Tube: add "-T" to sales code Reel: add "-R"
ZSC31010KIT	ZSC31010 SSC Evaluation Kit: Communication Board, SSC Board, Sensor Replacement Board, Evaluation Software, USB Cable, 5 IC Samples	Kit

Please contact ZMDI Sales for additional options.

Contact ZMDI Sales for support and sales of ZMDI's ZSC31010 Mass Calibration System.

^{*} Exception: The digital circuit fault coverage is 94% for production testing (reference AEC-Q100-007).





12 Related Documents

Document	File Name
ZACwire SSC Evaluation Kit Documentation for ZSC31010 and ZSC31015	ZACwire_SSC_Evaluation_Kit_rev_X_xy.pdf
ZSC31010/15 Technical Notes – Calibration Sequence, DLL and EXE	ZSC31010_15_Tech_Notes_Cal_DLL_EXE_rev_X_xy.pdf
SSC Kits Feature Sheet (includes ordering codes and prices)	SSC_Evaluation_Kits_FeatureSheet_Rev_rev_X_xy.pdf
ZSC31010 RBic _{Lite} ™ Errata Sheet – Rev C Production	ZSC31010_RBic_Lite_Errata_RevC_Prod_rev_X_xy.pdf
ZSC31010 RBic _{Lite} ™ Application Notes - In-Circuit Programming Boards	ZSC31010_RBic_Lite_App_Notes_In-Circuit_ Programming_rev_X_xy.pdf
ZSC31010 RBic _{Lite} ™ Die Dimensions and Pad Coordinates	ZSC31010_RBic_Lite_Tech_Notes_Die_Pads_rev_X_xy.pdf

Visit ZMDI's website <u>www.zmdi.com</u> or contact your nearest sales office for the latest version of these documents.

13 Definitions of Acronyms

ADCAnalog-to-Digital ConverterAFEAnalog Front-EndBUFBufferCMCommand ModeCMCCalibration MicrocontrollerDACDigital-to-Digital ConverterDNLDifferential NonlinearityDSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	Term	Description
AFEAnalog Front-EndBUFBufferCMCommand ModeCMCCalibration MicrocontrollerDACDigital-to-Digital ConverterDNLDifferential NonlinearityDSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMOrne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	ADC	Analog-to-Digital Converter
BUFBufferCMCommand ModeCMCCalibration MicrocontrollerDACDigital-to-Digital ConverterDNLDifferential NonlinearityDSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	AFE	Analog Front-End
CMCommand ModeCMCCalibration MicrocontrollerDACDigital-to-Digital ConverterDNLDifferential NonlinearityDSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOVIOne-Wire InterfacePOCPower-On ClearPORPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	BUF	Buffer
CMCCalibration MicrocontrollerDACDigital-to-Digital ConverterDNLDifferential NonlinearityDSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOVIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	СМ	Command Mode
DACDigital-to-Digital ConverterDNLDifferential NonlinearityDSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePORPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	CMC	Calibration Microcontroller
DNLDifferential NonlinearityDSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	DAC	Digital-to-Digital Converter
DSPDigital Signal ProcessorDUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	DNL	Differential Nonlinearity
DUTDevice Under TestESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	DSP	Digital Signal Processor
ESDElectrostatic DischargeFSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	DUT	Device Under Test
FSOFull-Scale OutputINLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	ESD	Electrostatic Discharge
INLIntegrated NonlinearityLSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	FSO	Full-Scale Output
LSBLeast Significant BitMUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	INL	Integrated Nonlinearity
MUXMultiplexerNOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	LSB	Least Significant Bit
NOMNormal Operation ModeOWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	MUX	Multiplexer
OWIOne-Wire InterfacePOCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	NOM	Normal Operation Mode
POCPower-On ClearPORPower-On Reset LevelPSRRPower Supply Rejection RatioPTATProportional To Absolute TemperatureRMRaw ModeSOTSecond Order Term	OWI	One-Wire Interface
POR Power-On Reset Level PSRR Power Supply Rejection Ratio PTAT Proportional To Absolute Temperature RM Raw Mode SOT Second Order Term	POC	Power-On Clear
PSRR Power Supply Rejection Ratio PTAT Proportional To Absolute Temperature RM Raw Mode SOT Second Order Term	POR	Power-On Reset Level
PTAT Proportional To Absolute Temperature RM Raw Mode SOT Second Order Term	PSRR	Power Supply Rejection Ratio
RM Raw Mode SOT Second Order Term	PTAT	Proportional To Absolute Temperature
SOT Second Order Term	RM	Raw Mode
	SOT	Second Order Term

 Data Sheet May 25, 2011
 © 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8 All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.
 45 of 46



RBic_{Lite}™ Low-Cost Sensor Signal Conditioner

14 Document Revision History

Revision	Date	Description
2.44	08-Apr-10	Clarification of part ordering codes and addition of document revision history.
2.5	27-Jul-10	Revision of product name from ZMD31010 to ZSC31010.
2.6	11-Nov-10	Removed reference to mass calibration kit; added footnote to short protection; added special measurement information (Table 3.3): revised stop bit definition; added EEPROM specifications to section 1.3 "Electrical Parameters." Added Table 6.1 "Storage and Soldering Conditions" to section 6 "Pin Configuration and Package." Corrected equation (2).
2.7	30-Mar-11	Revision in "Related Documents" table for the name of the kit document. Revision in Table 6.1 to match the maximum temperature range in Table 1.1. Updated trim tolerances in sections 4.1 and 4.2. Correction of formula in Table 4.1.
2.8	25-May-11	Revision of Table 5.1 to add column for defaults as of 48/2008. Revisions to description of T_{SETL} .

Sales and Further Info	rmation	www.zmdi.com	SSC@zmdi.com
Zentrum Mikroelektronik Dresden AG Grenzstrasse 28 01109 Dresden Germany	ZMD America, Inc. 8413 Excelsior Drive Suite 200 Madison, WI 53717 USA	Zentrum Mikroelektronik Dresden AG, Japan Office 2nd Floor, Shinbashi Tokyu Bldg. 4-21-3, Shinbashi, Minato-ku Tokyo, 105-0004 Japan	ZMD FAR EAST, Ltd. 3F, No. 51, Sec. 2, Keelung Road 11052 Taipei Taiwan
Phone +49 (0)351.8822.7.772 Fax +49 (0)351.8822.87.772	Phone +1 (608) 829-1987 Fax +1 (631) 549-2882	Phone +81.3.6895.7410 Fax +81.3.6895.7301	Phone +886 2 2377 8189 Fax +886 2 2377 8199

DISCLAIMER: This information applies to a product under development. Its characteristics and specifications are subject to change without notice. Zentrum Mikroelektronik Dresden AG (ZMD AG) assumes no obligation regarding future manufacture unless otherwise agreed to in writing. The information furnished hereby is believed to be true and accurate. However, under no circumstances shall ZMD AG be liable to any customer, licensee, or any other third party for any special, indirect, incidental, or consequential damages of any kind or nature whatsoever arising out of or in any way related to the furnishing, performance, or use of this technical data. ZMD AG hereby expressly disclaims any liability of ZMD AG to any customer, licensee or any other third party, and any such customer, licensee and any other third party hereby waives any liability of ZMD AG to any customer, licensee or any other third party, and any such customer, licensee and any other third party, hereby waives any liability of ZMD AG to any customer, licensee or any other third party, and any such customer, licensee and any other third party, hereby waives any liability of ZMD AG to any customer, licensee or any other third party, and any such customer, licensee and any other third party, hereby waives any liability of ZMD AG to any customer, licensee or any other third party and any such customer, licensee and any customer, warranty, tort (including negligence), strict liability, or otherwise.

Data Sheet	© 2011 Zentrum Mikroelektronik Dresden AG — Rev. 2.8	16 of 16
May 25, 2011	All rights reserved. The material contained herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner. The information furnished in this publication is subject to changes without notice.	40 01 40

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ZMDI:

<u>ZSC31010CAG1-R</u> <u>ZSC31010CAG1-T</u> <u>ZSC31010CEG1-R</u> <u>ZSC31010CEG1-T</u> <u>ZSC31010CIG1-R</u> <u>ZSC31010CIG1-R</u> <u>ZSC31010CIG1-R</u>